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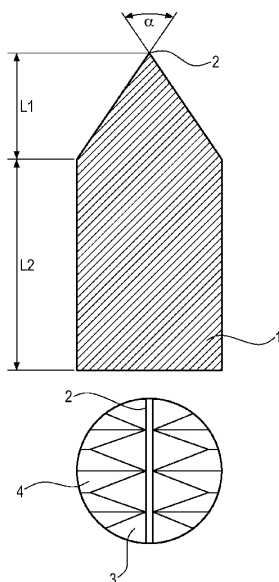
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- (54) **Title:** IMPROVED DEVICE FOR DRYING SEMICONDUCTOR SUBSTRATES

Fig. 1



- (57) **Abstract:** Device for drying disc-shaped substrates comprising an elongated body (1), which tapers upwards to form a wedge having an angle α between two upper surfaces and the upper edge (2) wherein the upper edge (2) is suitable for a disc-shaped substrate to be supported on, characterized in that an upper surface (3) comprises a groove (4) having an increasing groove depth with increasing distance from the upper edge (2).

WO 2021/121901 A1